505666008 09/11/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JAMES R PRZYBYLA	03/07/2018
JASON HOWER	03/07/2018
MICHAEL G MONROE	03/07/2018
GALEN P COOK	03/07/2018

RECEIVING PARTY DATA

Name:	Hewlett-Packard Development Company, L.P.	
Street Address:	11445 Compaq Center Drive West	
City:	Houston	
State/Country:	TEXAS	
Postal Code:	77070	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16493050

CORRESPONDENCE DATA

Fax Number: (970)778-4063

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: HP INC.

Address Line 1: 3390 E. HARMONY ROAD MS 35
Address Line 4: FORT COLLINS, COLORADO 80528

ATTORNEY DOCKET NUMBER:	85786310
NAME OF SUBMITTER:	TRACY J. KIMMEL
SIGNATURE:	/Tracy J. Kimmel/
DATE SIGNED:	09/11/2019

Total Attachments: 3

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PATENT 505666008 REEL: 050340 FRAME: 0024

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID:	84916126
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ASSIGNMENT OF PATENT APPLICATION

and in furtherance of my/our obligations to HEWLETT Limited Partnership having its principal place of busin subsidiaries and affiliates, agree to assign and transfer a	consideration, the receipt of which is hereby acknowledged, T-PACKARD DEVELOPMENT COMPANY, L.P., a Texas ness in Houston, Texas, (hereinafter HPDC), and to its nd hereby assign and transfer to HPDC, its successors and right of priority, in, to and under an application for Patent		
ADDITIVE MANUFACTURING WITH NOZZLES AT DIF	FERENT DIE WIDTHS		
Filing Date: March 12, 2018	Application No.: PCT/US2018/022036		
divisionals, and renewals of and substitutes for said appli	and any and all continuations, continuations-in-part (C-I-P's), ication for said Patent, and any and all other Patent of any re; and any reissues, or reexaminations, or extensions of said		
by HPDC, its successors, assigns, nominees or legal repre	my/our name for Patent in any country, to be held and enjoyed sentatives, to the full end of the term or terms for which said as fully and entirely as the same would have been held and made;		
AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC;			
applications as aforesaid, to issue to HPDC, as assignee of	any country or countries whose duty it is to issue patents on f the entire right, title and interest, any and all Patent for said granted on or as a result of the application aforesaid, in		
	cord to insert the filing date and application number of said tle set forth above, as soon as the same shall have been made		
IN WITNESS WHEREOF, I/we hereunto set my/our harmonic for the set my/our harmonic for	nand(s) and seal(s): 3/7/18 Date		
Inventor's Signature	Date		
Jason Hower	· 		
First/Middle Name Last Name			
Rev 8/2014 (Assignment) Page	1 of 2		

PATENT REEL: 050340 FRAME: 0025

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID:	84916126
RECORD ID:	84916126

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPDC), and to its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPDC, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled:

ADDITIVE MANUFAÇ	TURING WITH NOZZLES	AT DIFFERENT DIE WIDTHS	
Filing Date: Ma	nrch 12, 2018	Application No.:	PCT/US2018/022036
divisionals, and renewa	ls of and substitutes for s	aid application for said Patent.	uations, continuations-in-part (C-I-P's), and any and all other Patent of any reexaminations, or extensions of said
by HPDC, its successor Patent respectively may	s, assigns, nominees or leg	gal representatives, to the full er xtended, as fully and entirely as	in any country, to be held and enjoyed nd of the term or terms for which said the same would have been held and
executed and will not ex time a request is made, perfect the title to said ir nominees or legal repressaid invention(s) or imprepapers, to execute all crightful oaths and declarategal representatives to improvement(s) in any ar and assistance are paid to the said that	acute any agreement in cor and without undue delay, ex- vention(s) or improvement(centatives, and I/we agree to ovement(s), said application ilsclaimers and divisionals, ations, and generally to do a obtain and enforce, for its aid all countries provided the by HPDC; uthorize and request the of , to issue to HPDC, as ass ment(s) which may be issue	nflict herewith, and I/we further of execute and deliver all such paper is), said application and said Patio communicate to HPDC, or to in and said Patent, to testify in an continuations, C-I-P's, reissue everything possible to aid HPDC, or their own benefit, proper patiexpenses which may be incurred expenses which may be incurred fficial of any country or countries signee of the entire right, title and	nerein assigned, and that I/we have not overaant and agree that I/we will, each is as may be necessary or desirable to ent, to HPDC, its successors, assigns, its nominee, all known facts respecting my legal proceedings, to sign all lawful and foreign applications, to make all its successors, assigns, nominees and tent protection for said invention(s) or if the tent in the tent protection is successive. The tent is to issue patents on its whose duty it is to issue patents on its different patent in the tent in the ten
l/we further authoria	ze and direct the attorney	s of record to insert the filing D and title set forth above, as so	date and application number of said on as the same shall have been made
	EOF, I/we hereunto set m	ny/our hand(s) and seal(s):	
inventor's Signature		Date	
James R.	Przybyla		
First/Middle Name	Last Name		, ,
- Della 1	// Her	7 3/	17/18
Inventor's Signature		Date	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
Jason	Hower		
First/Middle Name	Last Name		

Page 1 of 2

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HP Inc. 3390 E. Harmony Road Mail Stop 35			PATENT APPLICATION
Fort Collins, Colorado 80528		RECORD ID:	84916126
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Inventor's Signature		Date	
Michael G.	Monroe		
First/Middle Name	Last Name		3
Calar Ca		3	17/18
Inventor's Signature		Date	• }
Galen P.	Cook		
First/Middle Name	Last Name		
			•
Inventor's Signature		Date	
First/Middle Name	Last Name		
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Inventor's Signature		Date	
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First/Middle Name	Last Name		
Inventor's Signature		Date	4444
First/Middle Name	Last Name		
Inventor's Signature		Date	
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First/Middle Name	Last Name		

Page 2 of 2

Rev 8/2014 (Assignment)